

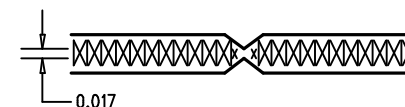
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.094	7	+	PLTD
0.055	5	×	PLTD
0.035	21	□	PLTD
0.07	2	◇	NPLTD
0.125	4	⊗	PLTD
0.015	177	⊗	PLTD
0.21	4	A	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY	1630 McCarthy Blvd Milpitas, CA 95035 PH: (408)432-1900		
	INIT	DATE				
DRAWN						
CHECK						
DESIGN	KIM T.	02-11-02				
ENGR	HARESH P.	02-11-02				
			TITLE: Fabrication Drawing			
			HIGH EFFICIENCY NOTEBOOK CPU PWR SUPPLY			
			SIZE A		DEMO DC389A-2 * LTC3778EF	REV. A
SCALE = NONE			DES- 0000		SHT 1 of 1	